

HT3500, HT5000 Thermally Conductive Gap Fillers

BENEFITS AND FEATURES

- High thermal performance
- low contact resistance
- Easily dispensable and reworkable
- High compressibility for low stress applications
- Reliable thermal performance
- No pump out and cracking risk

OVERVIEW

Honeywell HT one-part series Gap Filler provides an effective thermal properties and high conformability with its high compressibility. It is formulated to deliver high dispense rates for improved productivity, long-term reliability performance and easy reworkability. It is designed to minimize thermal resistance at interfaces, maintain excellent performance through reliability testing, and provide scalable application at a competitive cost.



TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Automotive electronics
- Power supplies & semiconductors
- Memory & power modules
- Power electronics

Property	HT3500	HT5000	Test Method
Feature	Silicone-based	Silicone-based	-
	Pre-cured	Pre-cured	-
Color	Dark red	Grey	Visual
Specific Gravity	3.2	3.4	ASTM D792
Thermal Conductivity (W/m-K)	3.5	5.0	ASTM D5470
Thermal Impedance (°C-cm ² /W)	<0.35	<0.25	ASTM D5470 at BLT
Minimum BLT(mm)	0.10	0.05	-
Dispense Rate (g/min)	>10	>10	90Psi, 30cc EFD syringe
Out Gassing (TML)	<0.5%	<0.5%	ASTM E595
Storage Condition	RT	RT	-
Shelf (month)	12	12	-

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